

Title

IST3932 Specification 196x65 *STN Driver*

文件編號 DOC# 版次 Rev IST-RD-0125 **003**

生效日期 Effective Date:
05/29/2013

Specification

資料中心參考文件用章 For Reference Only

2013.04.17



聯合聚晶股份有限公司 Integrated Solution Technology Inc

Written by Department	Written by / Date	Approved by QRA Manager	Issued by D.C.C.
R&D	Michael 05/29/2013	Bonnie Lee 05/29/2013	Bonnie Lee 05/29/2013

Controlled by DCC

Copy List

Code Name	100	200	300	400	500	600	700
	HR	S/M	MFG	R&D	СН	QRA	MIS
Dept.				✓	✓	✓	



Title

IST3932 Specification 196x65 *STN Driver*

文件編號 DOC# 版次 Rev IST-RD-0125 **003**

生效日期 Effective Date: 05/29/2013

文件變更履歷頁

Document Change History

版次	變更項次	變更內容簡述	變更依據文	撰寫者	生效日期
Rev.	Change Items#	Change Description	件號碼	Writer	Eff. Date
			ECN#		
P001		New Release	E07120009	Plato	07/27/2012
P002	-	Pad location Update	E08120001	Plato	08/13/2012
	P46	DC CHARACTERISTICS			
001	P47	Dynamic Current Consumption	E03130003	Plata	03/07/2013
001	P47	Static Current Consumption	E03130003	Plato	03/07/2013
		Remove "Preliminary "			
	P21	Modify ADC value;			
	P27	Modify SEG direction Modify RESET value		Michael	04/17/2013
002	P37	Add CTOFT value table	E04130012		
002	P43	Add C* value			
	P46	Add bias value			
	P52~56	Remove "2.2uf or above"			
	P20~P35	Remove temperature sensor items			
003	P22~P36	Updated the command description sequence	E05130009	Michael	05/29/2013
	P42	Updated the system cycle time and pulse width			
接網	賣 CONTINUA	ATION 是 YES;	否 NO		

This document is the exclusive property of *IST* (Integrated Solutions Technology, Inc.) and shall not be reproduced or copied or transformed to any other format without prior permission of *IST* 本資料爲 **聯合聚晶** 專有之財產,非經許可,不得複製,翻印或轉變成其他形式使用.

INTRODUCTION	2
FEATURES	2
BLOCK DIAGRAM	3
PAD CONFIGURATION	4
PAD CENTER COORDINATES	5
PAD DESCRIPTION	8
Power Supply	8
System Control	8
Micro-Controller Interface	9
LCD Driver Outputs	10
I/O PIN ITO Resister Limitation	
FUNCTIONAL DESCRIPTION	11
Microprocessor Interface	11
Display RAM Address Mapping	20
Reset Initialization	21
Command Table	
COMMAND DESCRIPTION	
ABSOLUTE MAXIMUM RATINGS	39
DC CHARACTERISTICS	40
AC CHARACTERISTICS	42
REFERENCE APPLICATIONS	46
ITO CONNECTION	51

INTRODUCTION

The IST3932 is a single chip driver & controller LSI for graphic dot-matrix liquid crystal display systems. This chip can be connected directly to a microprocessor, accepts serial or 8-bit parallel display data from the microprocessor, stores the display data in an on-chip display data RAM of 65 x 196 bits and generates a liquid crystal display drive signal independent of the microprocessor. It provides a high-flexible display section due to 1-to-1 correspondence between on-chip display data RAM bits and LCD panel pixels. It contains 65 common driver circuits and 196 segment driver circuits, so that a single chip can drive a 65 x 196 dot display.

This chip is able to minimize power consumption because it performs display data RAM read / write operation with no external operation clock. In addition, because it contains power supply circuits necessary to drive liquid crystal, which is a display clock oscillator circuit, high performance voltage converter circuit, high-accuracy voltage regulator circuit, low power consumption voltage divider resistors and OP-Amps for liquid crystal driver power voltage, it is possible to make the lowest power consumption display system with the fewest components for high performance portable systems.

FEATURES

Power Supply

Logic Power VDD1 –GROUND = 2.4V ~ 3.6V
 Analog Power VDD2/VDD3 –GROUND = 2.4V ~

3.6V

- LCD Driving V0 - GROUND = 13.5V (Max)

Microprocessor Interface

- High-speed 8080/6800-series 8-bit parallel bi-directional interface
- Serial 3/4 line Write/Read interface
- IIC Write/Read interface

Display Driver Output Circuits

- 65 common outputs / 196 segment outputs
- Display Duty = 1/1~ 1/65
- Applicable Bias: 1/6 ~ 1/11

Various Function Set

- Display On/Off control
- Set display starting line,
- Set row/column address
- Software reset
- Read Status
- Reverse display
- Select Bias
- Set Duty
- COM/SEG output direction control
- Display power control
- LCD Contrast (V0) control
- MTP(Multi-Times-Programming) Contrast adjust

On-chip Display Data RAM

- RAM size : 65x196 =12,740 bits

Built-in Analog Circuit

- Reduced external parts (1~5 capacitors only, depending on panel loading)
- On-chip oscillator circuit for display clock (external clock can also be used)
- High performance voltage converter (with booster ratios x5)
- High accuracy reference voltage generator
- Electronic contrast control (256 steps)
- Embedded V0 Voltage regulator
- High performance voltage follower (V1 ~ V4 voltage generator with output buffer)
- Temperature compensation on frame frequency and V0 voltage

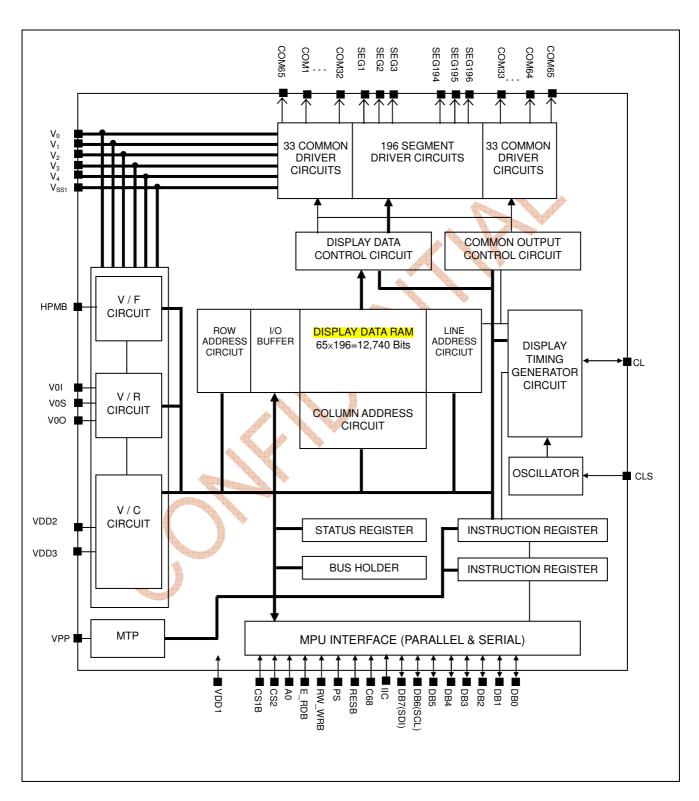
Operating Temperatures

 Wide range of operating temperatures from -30°C to 80°C

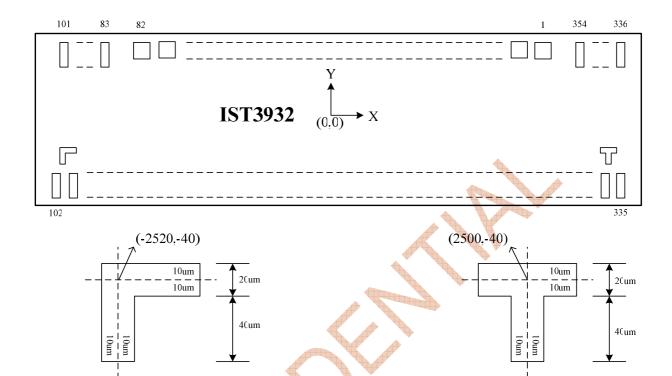
Package Type

COG(Gold-bumped bared chip)

BLOCK DIAGRAM



PAD CONFIGURATION



Chip Size	5223 um x 600 um (Scribe Line Exclude)							
Bump Pitch	22um (min)							
Bump Spacing	12um (min)							
Pump Sizo/V*V	32 x 50 um2	Pad No = 1 ~82						
Bump Size(X*Y)	10 x 150 um2	Pad No =83 ~ 354						
Bump Height	12um (Typ)							
Chip Thickness	300um (Typ)							

PAD CENTER COORDINATES

Pad No.	Pin Name	X(um)	Y(um)	Pad No.	Pin Name	X(um)	Y(um)	Pad No.	Pin Name	X(um)	Y(um)
1	NC	2025	263	51	TEST2	-475	263	101	NC	-2563	214
2	NC	1975	263	52	VOP	-525	263	102	NC	-2563	-214
3	NC	1925	263	53	VDD1	-575	263	103	COM<31>	-2541	-214
4	NC	1875	263	54	VDD1	-625	263	104	COM<29>	-2519	-214
5	NC	1825	263	55	VDD2	-675	263	105	COM<27>	-2497	-214
6	NC	1775	263	56	VDD2	-725	263	106	COM<25>	-2475	-214
7	NC	1725	263	57	VDD3	-775	263	107	COM<23>	-2453	-214
8	NC	1675	263	58	VDD3	-825	263	108	COM<21>	-2431	-214
9	VPP	1625	263	59	VDD3	-875	263	109	COM<19>	-2409	-214
10	VPP	1575	263	60	VDD3	-925	263	110	COM<17>	-2387	-214
11	VSS1	1525	263	61	V4	-975	263	111	COM<15>	-2365	-214
12	VDD1	1475	263	62	V3	-1025	263	112	COM<13>	-2343	-214
13	C68	1425	263	63	V2	-1075	263	113	COM<11>	-2321	-214
14	PS	1375	263	64	V1	-1125	263	114	COM<9>	-2299	-214
15	IIC	1325	263	65	VOS	-1175	263	115	COM<7>	-2277	-214
16	CLS	1275	263	66	VOS	-1225	263	116	COM<5>	-2255	-214
17	VSS1	1225	263	67	VOI	-1275	263	117	COM<3>	-2233	-214
18	VDD1	1175	263	68	VOI	-1325	263	118	COM<1>	-2211	-214
19	WRB	1125	263	69	VOI	-1375	263	119	NC	-2189	-214
20	RDB	1075	263	70	VOI	-1425	263	120	NC	-2167	-214
21	VSS1	1025	263	71	V0O	-1475	263	121	SEG<196>	-2145	-214
22	VDD1	975	263	72	V0O	-1525	263	122	SEG<195>	-2123	-214
23	DB<7>	925	263	73	VOO	-1575	263	123	SEG<194>	-2101	-214
24	DB<6>	875	263	74	VOO	-1625	263	124	SEG<193>	-2079	-214
25	DB<5>	825	263	75	NC	-1675	263	125	SEG<192>	-2057	-214
26	DB<4>	775	263	76	NC	-1725	263	126	SEG<191>	-2035	-214
27	DB<3>	725	263	77	NC	-1775	263	127	SEG<190>	-2013	-214
28	DB<2>	675	263	78	NC	-1825	263	128	SEG<189>	-1991	-214
29	DB<1>	625	263	79	NC	-1875	263	129	SEG<188>	-1969	-214
30	DB<0>	575	263	80	→ NC	-1925	263	130	SEG<187>	-1947	-214
31	VSS1	525	263	81	NC	-1975	263	131	SEG<186>	-1925	-214
32	VDD1	475	263	82	NC	-2025	263	132	SEG<185>	-1903	-214
33	RESB	425	263	83	NC	-2167	214	133	SEG<184>	-1881	-214
34	A0	375	263	84	COM<65>	-2189	214	134	SEG<183>	-1859	-214
35	CS1B	325	263	85	COM<63>	-2211	214	135	SEG<182>	-1837	-214
36	CS2	275	263	86	COM<61>	-2233	214	136	SEG<181>	-1815	-214
37	CL	225	263	87	COM<59>	-2255	214	137	SEG<180>	-1793	-214
38	TEST3	175	263	88	COM<57>	-2277	214	138	SEG<179>	-1771	-214
39	HPMB	125	263	89	COM<55>	-2299	214	139	SEG<178>	-1749	-214
40	VSS1	75	263	90	COM<53>	-2321	214	140	SEG<177>	-1727	-214
41	VSS1	25	263	91	COM<51>	-2343	214	141	SEG<176>	-1705	-214
42	VSS1	-25	263	92	COM<49>	-2365	214	142	SEG<175>	-1683	-214
43	VSS1	-75	263	93	COM<47>	-2387	214	143	SEG<174>	-1661	-214
44	VSS4	-125	263	94	COM<45>	-2409	214	144	SEG<173>	-1639	-214
45	VSS4	-175	263	95	COM<43>	-2431	214	145	SEG<172>	-1617	-214
46	VSS2	-225	263	96	COM<41>	-2453	214	146	SEG<171>	-1595	-214
47	VSS2	-275	263	97	COM<39>	-2475	214	147	SEG<170>	-1573	-214
48	VSS2	-325	263	98	COM<37>	-2497	214	148	SEG<169>	-1551	-214
49	VSS2	-375	263	99	COM<35>	-2519	214	149	SEG<168>	-1529	-214
50	TEST1	-425	263	100	COM<33>	-2541	214	150	SEG<167>	-1507	-214
	5	0	_50	. 50	50	_3	::	. 50		.507	

Pad No.	Pin Name	X(um)	Y(um)	Pad No.	Pin Name	X(um)	Y(um)	Pad No.	Pin Name	X(um)	Y(um)
151	SEG<166>	-1485	-214	201	SEG<116>	-385	-214	251	SEG<66>	715	-214
152	SEG<165>	-1463	-214	202	SEG<115>	-363	-214	252	SEG<65>	737	-214
153	SEG<164>	-1441	-214	203	SEG<114>	-341	-214	253	SEG<64>	759	-214
154	SEG<163>	-1419	-214	204	SEG<113>	-319	-214	254	SEG<63>	781	-214
155	SEG<162>	-1397	-214	205	SEG<112>	-297	-214	255	SEG<62>	803	-214
156	SEG<161>	-1375	-214	206	SEG<111>	-275	-214	256	SEG<61>	825	-214
157	SEG<160>	-1353	-214	207	SEG<110>	-253	-214	257	SEG<60>	847	-214
158	SEG<159>	-1331	-214	208	SEG<109>	-231	-214	258	SEG<59>	869	-214
159	SEG<158>	-1309	-214	209	SEG<108>	-209	-214	259	SEG<58>	891	-214
160	SEG<157>	-1287	-214	210	SEG<107>	-187	-214	260	SEG<57>	913	-214
161	SEG<156>	-1265	-214	211	SEG<106>	-165	-214	261	SEG<56>	935	-214
162	SEG<155>	-1243	-214	212	SEG<105>	-143	-214	262	SEG<55>	957	-214
163	SEG<154>	-1221	-214	213	SEG<104>	-121	-214	263	SEG<54>	979	-214
164	SEG<153>	-1199	-214	214	SEG<103>	-99	-214	264	SEG<53>	1001	-214
165	SEG<152>	-1177	-214	215	SEG<102>	-77	-214	265	SEG<52>	1023	-214
166	SEG<151>	-1155	-214	216	SEG<101>	-55	-214	266	SEG<51>	1045	-214
167	SEG<150>	-1133	-214	217	SEG<100>	-33	-214	267	SEG<50>	1067	-214
168	SEG<149>	-1111	-214	218	SEG<99>	-11	-214	268	SEG<49>	1089	-214
169	SEG<148>	-1089	-214	219	SEG<98>	11	-214	269	SEG<48>	1111	-214
170	SEG<147>	-1067	-214	220	SEG<97>	33	-214	270	SEG<47>	1133	-214
171	SEG<146>	-1045	-214	221	SEG<96>	55	-214	271	SEG<46>	1155	-214
172	SEG<145>	-1023	-214	222	SEG<95>	77	-214	272	SEG<45>	1177	-214
173	SEG<144>	-1001	-214	223	SEG<94>	99	-214	273	SEG<44>	1199	-214
174	SEG<143>	-979	-214	224	SEG<93>	121	-214	274	SEG<43>	1221	-214
175	SEG<142>	-957	-214	225	SEG<92>	143	-214	275	SEG<42>	1243	-214
176	SEG<141>	-935	-214	226	SEG<91>	165	-214	276	SEG<41>	1265	-214
177	SEG<140>	-913	-214	227	SEG<90>	187	-214	277	SEG<40>	1287	-214
178	SEG<139>	-891	-214	228 ﴿	SEG<89>	209	-214	278	SEG<39>	1309	-214
179	SEG<138>	-869	-214	229	SEG<88>	231	-214	279	SEG<38>	1331	-214
180	SEG<137>	-847	-214	230	SEG<87>	253	-214	280	SEG<37>	1353	-214
181	SEG<136>	-825	-214 🚕	231	SEG<86>	275	-214	281	SEG<36>	1375	-214
182	SEG<135>	-803	-214	232	SEG<85>	297	-214	282	SEG<35>	1397	-214
183	SEG<134>	-781	-214	233	SEG<84>	319	-214	283	SEG<34>	1419	-214
184	SEG<133>	-759	-214	234	SEG<83>	341	-214	284	SEG<33>	1441	-214
185	SEG<132>	-737	-214	235	SEG<82>	363	-214	285	SEG<32>	1463	-214
186	SEG<131>	-715	-214	236	SEG<81>	385	-214	286	SEG<31>	1485	-214
187	SEG<130>	-693	-214	237	SEG<80>	407	-214	287	SEG<30>	1507	-214
188	SEG<129>	-671	-214	238	SEG<79>	429	-214	288	SEG<29>	1529	-214
189	SEG<128>	-649 🦣	-214	239	SEG<78>	451	-214	289	SEG<28>	1551	-214
190	SEG<127>	-627	-214	240	SEG<77>	473	-214	290	SEG<27>	1573	-214
191	SEG<126>	-605	-214	241	SEG<76>	495	-214	291	SEG<26>	1595	-214
192	SEG<125>	-583	-214	242	SEG<75>	517	-214	292	SEG<25>	1617	-214
193	SEG<124>	-561	-214	243	SEG<74>	539	-214	293	SEG<24>	1639	-214
194	SEG<123>	-539	-214	244	SEG<73>	561	-214	294	SEG<23>	1661	-214
195	SEG<122>	-517	-214	245	SEG<72>	583	-214	295	SEG<22>	1683	-214
196	SEG<121>	-495	-214	246	SEG<71>	605	-214	296	SEG<21>	1705	-214
197	SEG<120>	-473	-214	247	SEG<70>	627	-214	297	SEG<20>	1727	-214
198	SEG<119>	-451	-214	248	SEG<69>	649	-214	298	SEG<19>	1749	-214
199	SEG<118>	-429	-214	249	SEG<68>	671	-214	299	SEG<18>	1771	-214
200	SEG<117>	-407	-214	250	SEG<67>	693	-214	300	SEG<17>	1793	-214

Pad No.	Pin Name	X(um)	Y(um)	Pad No.	Pin Name	X(um)	Y(um)	Pad No.	Pin Name	X(um)	Y(um)
301	SEG<16>	1815	-214	351	COM<62>	2233	214				
302	SEG<15>	1837	-214	352	COM<64>	2211	214				
303	SEG<14>	1859	-214	353	COM<65>	2189	214				
304	SEG<13>	1881	-214	354	NC	2167	214				
305	SEG<12>	1903	-214	(END)							
306	SEG<11>	1925	-214	, ,							
307	SEG<10>	1947	-214								
308	SEG<9>	1969	-214								
309	SEG<8>	1991	-214								
310	SEG<7>	2013	-214								
311	SEG<6>	2035	-214								
312	SEG<5>	2057	-214								
313	SEG<4>	2079	-214								
314	SEG<3>	2101	-214							<u> </u>	
315	SEG<2>	2123	-214								
316	SEG<1>	2145	-214								
317	NC	2167	-214				A				
318	NC	2189	-214								
319	COM<2>	2211	-214								
320	COM<4>	2233	-214			4	*				
321	COM<6>	2255	-214			400-					
322	COM<8>	2277	-214								
323	COM<10>	2299	-214								
324	COM<12>	2321	-214		4						
325	COM<14>	2343	-214				*				
326	COM<16>	2365	-214								
327	COM<18>	2387	-214								
328	COM<20>	2409	-214								
329	COM<22>	2431	-214	4	7						
330	COM<24>	2453	-214	4 /							
331	COM<26>	2475	-214								
332	COM<28>	2497	-214	# #							
333	COM<30>	2519	-214		•						
334	COM<32>	2541	-214								
335	NC	2563	-214	A							
336	NC	2563	214	-							
337	COM<34>	2541	214								
338	COM<36>	2519	214								
339	COM<38>	2497	214								
340	COM<40>	2475	214								
341	COM<42>	2453	214								
342	COM<44>	2431	214								
343	COM<46>	2409	214								
344	COM<48>	2387	214								
345	COM<50>	2365	214								
346	COM<52>	2343	214								
347	COM<54>	2321	214								
348	COM<56>	2299	214								
349	COM<58>	2277	214								
350	COM<60>	2255	214								

PAD DESCRIPTION

Power Supply

Name	I/O			Description					
VDD1	Power Supply	Logic power supp The input voltage		/DD1 ≤ 3.6V					
VDD2	Supply	The input voltage	OCDC Power source The input voltage range is 2.4V ≤ VDD2 ≤ 3.6V						
VDD3	Power Supply		OSC Power source, Analog power supply the input voltage range is 2.4V ≤ VDD3 ≤ 3.6V						
VSS1	Power Supply	Logic Ground							
VSS2	Power Supply	DCDC Ground							
VSS4	Power Supply	Analog Ground	alog Ground						
VPP	Power Supply		MTP (Multi-Times-Program) power source. Just keep open when not in MTP programming section						
V0 V1		LCD driver supply voltages The voltage determined by LCD pixel is impedance-converted by an operational amplifier for application. Voltages should have the following relationship; V0 ≥ V1 ≥ V2 ≥ V3 ≥ V4 ≥ VSS1/VSS2/VSS4=GROUND When the internal power circuit is active, these voltages are generated as following a following table according to the state of LCD bias.							
V2	I/O	LCD bias	V1	V2	V3	V4			
V3		1/11 bias	(10/11) x V0	(9/11) x V0	(2/11) x V0	(1/11) x V0			
V4		1/10 bias	(9/10) x V0	(8/10) x V0	(2/10) x V0	(1/10) x V0			
		1/9 bias	(8/9) x V0	(7/9) x V0	(2/9) x V0	(1/9) x V0			
		1/8 bias	(7/8) x V0	(6/8) x V0	(2/8) x V0	(1/8) x V0			
		1/7 bias	(6/7) x V0	(5/7) x V0	(2/7) x V0	(1/7) x V0			
		1/6 bias	(5/6) x V0	(4/6) x V0	(2/6) x V0	(1/6) x V0			
System Co	System Control								

Name	I/O	Description
CLS	_	Built-in oscillator circuit enable / disable select pin CLS = "H": enable (this pin is used together with digital command) - CLS = "L": disable (external display clock input through CL pin)
CL	I/O	External clock input pin, It must fix to VSS1 or VDD1 when CLS is "H"
НРМВ	ı	Power circuit driving ability control - HPMB = "H": Normal mode - HPMB = "L": High power mode

Micro-Controller Interface

Name	I/O)esc	ription			
RESB	I		re Reset inp RESB is "L",		ı is exed	cuted	I.			
		Parallel	/ serial data	input selec	ct input,	and	IIC must set to	"H"		
		PS	Interface mode	Chip select	Data instruc		Data	Read / Write	Serial clock	
PS	1	Н	Parallel	CS1B, CS2	A0	١	DB0 to DB7	E_RDB RW_WRB		
		L	L Spi3/spi4 CS1B, - SDI (DB7) Write/Read SCL (<note> In serial mode, DB0 to DB5 and E_RDB and RW_WRB must be fixed to either "H" or "L". It</note>							
		<note> define as</note>	In serial mode, ID0 when IIC ir	DB0 to DB5 a nterface (IIC="	and E_RD 'L") is use	B and	I RW_WRB must b	e fixed to either "H"	or "L". It also	
C68	I	- C68 =	icroprocessor Interface Select input pin in parallel mode(when IIC="H",PS="H") C68 = "H" : 6800-series MPU interface C68 = "L" : 8080-series MPU interface also define as ID1 when IIC interface(IIC="L") is use							
CS1B			lect input pir							
CS2	ı						CS1B is "L" and an impedance.	d CS2 is "H". w	nen cnip	
IIC	I	IIC mod	elect is non-active, DB0 to DB7 may be high impedance. C mode selection pin. IIC mode is enabled when IIC is "L", CS1B must fix at "L", and it isabled when IIC is "H"							
A0	1	- A0 =	Register select input pin - A0 = "H" : DB0 to DB7 are display data - A0 = "L" : DB0 to DB7 are control data							
			Write execut					Dana dallar		
		C68	C68 MPU Type RW_WRB				Description control input pin			
RW_WRB	т н	H 6800-serie		es R	RW		- RW = "H" : read - RW = "L" : write			
		L	8080-serie	es /W	'RB	The	te enable clock data on DB0 to e of the /WRB	DB7 are latche	ed at the rising	
		Read / \	Write execut	ion control	pin					
		C68	MPU Type	e E_R[escription		
E_RDB		Read / Write control input pin - RW = "H" : When E is "H", DB0 to DB7 are in output status RW = "L": The data on DB0 to DB7 are latch at the falling edge the E signal. Read enable clock input pin When / RDB is "L", DB0 to DB7 are in an output status.								
								n an output		
							ed to the standa	ard 8-bit microp	rocessor data	
DB0 bus. When the serial interface selected (PS = "L"); - DB0 to DB5 : high impedance										
to DB7	I/O									
DB7		- DB7 :	- DB6 : serial input clock (SCL) - DB7 : serial input data (SDI) When chip select is not active, DB0 to DB7 may be high impedance.							
VOP	I/O		, must keep							

V0I	- 1	V0I is the power of COM and SEG driver
VOS		V0S is the sensor of the V0 generator
V0O	0	V0O is the output of V0 generator
TEST1~2	I/O	Test pins, must keep them open
TEST3	ı	Test pin, let it "L" when not be used

LCD Driver Outputs

Name	I/O		Desci	ription							
		LCD segment driver on The display data and		the output voltage of s	egment driver.						
		Dianlay data	M	Segment driver output voltage							
SEC1.		Display data	IVI	Normal display	Reverse display						
SEG1 ~ SEG196	0	Н	Н	V0							
GEG130		Н	L	GROUND	V3						
		L	Н	V2	V0						
		L	L	V3	GROUND						
		Power sa	ave mode	GROUND	GROUND						
		LCD common driver of The internal scanning driver.		gnal control the outpu	it voltage of segment						
0014		Scan data	M	Common drive	r output voltage						
COM1 ~ COM65	0	Н	H	GRO	UND						
COMOS		Н		V	0						
		L	H	V	′1						
		L	L	V4							
		Power save mode GROUND									

I/O PIN ITO Resister Limitation

PIN Name	ITO Resister
VDD1, VDD3, VSS1, VSS4,V0O,V0I	<200Ω
VDD2, VSS2,	<100Ω
V0,V1,V2,V3,V4,V0S	<300Ω
CS1B,CS2,RW_WRB,E_RDB,A0,DB0~DB7	<1ΚΩ
RESB	<10ΚΩ
CL,C68,PS,HPMB,CLS,TEST3,IIC,VOP	No Limitation
TEST1, TEST2	Floating
VPP	<200Ω

FUNCTIONAL DESCRIPTION

Microprocessor Interface

Chip select control

There are CS1B and CS2 pins for chip selection. The IST3932 can interface with an MPU only when CS1B is "L" and CS2 is "H". When these pins are set to any other combination, A0, E_RDB, and RW_WRB inputs are disabled and DB0 to DB7 are high impedance. In case of serial interface, the internal shift registers and the counter are reset.

MPU Interface types

IST3932 has five types of MPU interface, which are three serial and two parallel interfaces. This parallel or

serial interface is determined by IIC, PS, C68 pin as shown below.

IIC	PS	C68	Type	Interface mode
Н	Н	Н	Parallel	6800-series MPU mode
Н	Н	L	Parallel	8080-series MPU mod
Н	L	Н	Serial	3-Line SPI Serial-mode
Н	L	L	Serial	4-Line SPI Serial-mode
L	*	*	Serial	IIC Serial-mode

^{*}x: PS/C68 is use as ID1/ID0, IIC host can use ID1/ID0 to select difference IIC device.

Parallel Interface (IIC="H" PS = "H")

The 8-bit bi-directional data bus is used in parallel interface and the type of MPU is selected by C68. The type of data transfer is determined by signals at A0, E_RDB and RW_WRB as shown below.

C68	CS1B	CS2	Α0	E_RDB	RW_WRB	DB0 to DB7	MPU bus
Н	CS1B	CS2	A0	E	RW	DB0 to DB7	6800-series
L	CS1B	CS2	A0	/RDB	/WRB	DB0 to DB7	8080-series

Common	6800-	series	8080-	series	
A 0	E_RDB (E)	RW_WRB (RW)	E_RDB (/RDB)	RW_WRB (/WRB)	Description
Н	Н	H	L	Н	Display data read out
Н	Н	L	H	L	Display data write
L	H	Н	L	Н	Register status read
L	Н		Н	L	Writes to internal register (instruction)

Serial Interface (IIC="H" PS = "L")

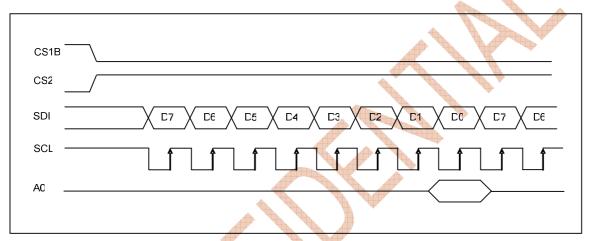
When IIC = "H" PS = "L", the IST3932 is configured as Serial interface(4-line or 3-line), the serial data can be input through DB7 (SDI) and serial clock can be input through DB6 (SCL).

When the chip is not selected, the shift register & serial data counter will be reset and SDI & SCL will also be disabled internally.

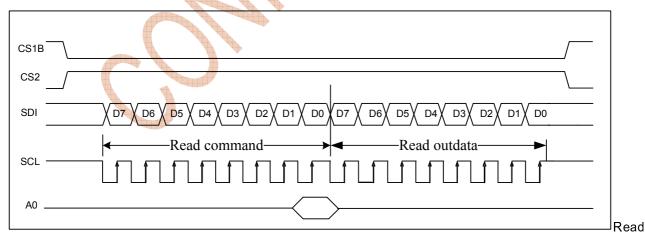
4-Line Serial Interface (IIC="H" PS = "L" C68="L")

When the chip is selected (CS1B="L", CS2="H"), the serial data can be shifted in sequentially at the rising edge of SCL and transferred to 8-bit parallel data internally; at the eighth SCL rising edge, A0 will also be sampled to decide these 8-bit data is interpreted as command or display data.

4-Line Serial Interface Timing



Write operation of 4-Line SPI

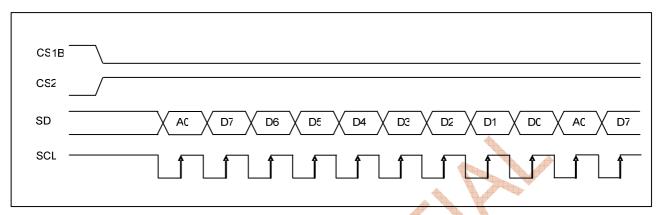


operation of 4-Line SPI

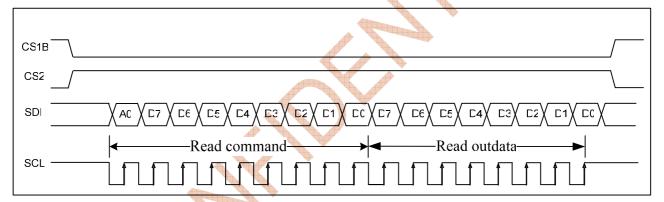
3-Line Serial Interface (IIC="H" PS = "L" C68="H")

In 3-Line interface, A0 signal is not available and the 1st output of SDI will be treated as A0 flag.

3-Line Serial Interface Timing



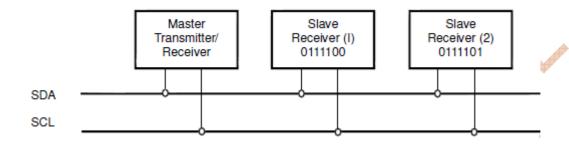
Write operation of 3-Line SPI



Read operation of 3-Line SPI

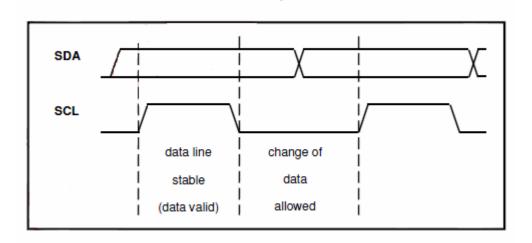
IIC Interface

As 80/68-sreies or 4-line serial interface, The IST3932 also supports standard IIC interface for command & display data communication. The IIC interface is a bi-directional, two-line serial interface, the two lines are a Serial Data line(SDA) and a Serial Clock line(SCL), both lines must be connected to a positive supply via a pull-up resistor. Data transfer may be initiated only when the bus is not busy.



Bit Transfer

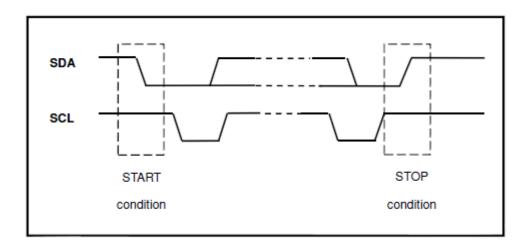
One data bit is transferred during each clock pulse. The data on the SDA line must remain stable during the HIGH period of the clock pulse, because changes in the data line at this time will be interpreted as a control signal



START and STOP Conditions

Both data and clock lines remain HIGH when the bus is not busy. A HIGH-to-LOW transition of the data line, while the clock is HIGH is defined as the START condition (S). A LOW-to-HIGH transition of the data line while the clock is HIGH is defined as the STOP condition (P).

Document No.:IST-RD-0125 Version: 003 MAY. 2013



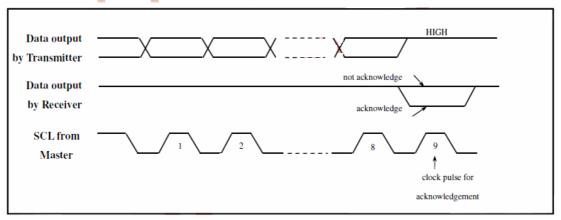
ACKNOWLEDGE

Each byte of eight bits is followed by an acknowledge bit. The acknowledge bit is a HIGH signal put on the bus by the transmitter(to release the SDA control and waiting for receiver's acknowledgement), during which time the master generates an extra acknowledge related clock pulse.

A slave receiver which is addressed must generate an acknowledge after the reception of each byte. A master receiver must also generate an acknowledge after the reception of each byte that has been clocked out of the slave transmitter.

The device that acknowledge must pull-down the SDA line during the acknowledge clock pulse, so that the SDA line is stable LOW during the HIGH period of the acknowledge related clock pulse (set-up and hold times must be taken into consideration).

A master receiver must signal and end-of-data to the transmitter by not generating an acknowledge on the last byte that has been clocked out of the slave. In this event the transmitter must leave the data line HIGH to enable the master to generate a STOP condition.



IIC Interface Protocol

The IIC transmitting is initiated with a START condition (S) from the IIC-bus Master and followed by a slave address. Two 7-bit slave address (0111100, 0111101, 0111110, 0111111) are reserved for the IST3932. The least significant bit of the slave address (ID) is configured by C68 and PS pin to decide is the slave address is 0111100 (C68=0/PS=0) or 0111101 (C68=0/PS=1) or 0111110(C68=1/PS=0) or 0111111(C68=1/PS=1). The 8th bit follows the previous 7-bit address is the data direction bit (R/W) -- '0' indicates Master data transmission (WRITE), '1' indicates Master data request (READ).

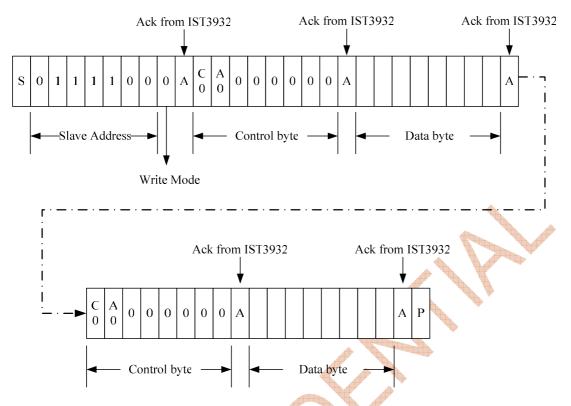
WRITE Mode (Master transmits data to Slave, R/W=0)

Write mode includes Slave address byte, control byte & data byte. After acknowledgement, one or more command words follow which define the status of the addressed slaves. A command word consists of a control byte, which defines C0 and A0, and a data byte. The control and data bytes are also acknowledged by all addressed slaves on the bus.

The C0 bit indicates the continuation of the command, please just set C0=1 during the whole Write transmitting period. The A0 bit decides the interpretation of the data byte. If A0 bit is 0, the data byte will be interpreted as command index, if A0 bit is 1, the databyte will be interpreted as command data.

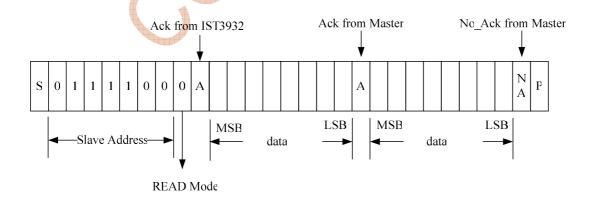
A data transfer is always terminated by a STOP condition (P)generated by the master. However, if master still wishes to communicate on the bus, it can generate a repeated START condition and address another slave without first generating a STOP condition.

WRITE Mode



READ Mode (Master requests data from Slave, R/W=1)

At the moment of the first acknowledge, the Master-transmitter becomes a Master-receiver and the Slave-receiver becomes a Slave transmitter. The first acknowledge is still generated by the slave, but the following data bytes' acknowledgement are generated by Master. The STOP and Re-START conditions are generated by Master. If Master wants to stop the data request, after the last data byte has been received, send a Non-Acknowledge condition (keep SDA at HIGH) and trigger a STOP condition.



Busy Flag

The Busy Flag indicates whether the IST3932 is still during operation or not. When DB7 is "H" in read status operation, this device is in busy status and will accept only read status instruction. If the write cycle time is correct, the microprocessor needs not to check this flag before each instruction to improve the operation efficiency.

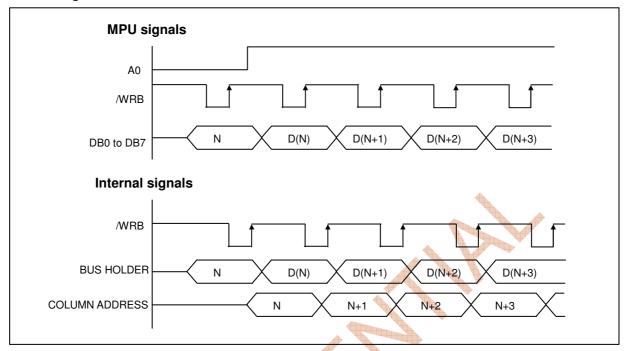
Data Transfer

The IST3932 has a I/O bus holder stage to temporary storage the data received from MPU or on-chip RAM data requesting from MPU to read.

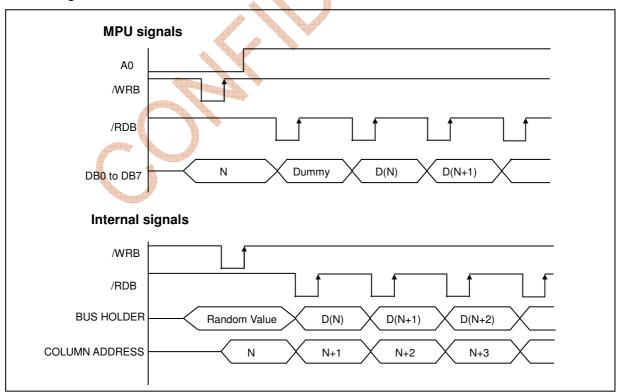
When user wants to read out the on-chip RAM data, after setting the address, a "dummy read" cycle must be inserted first to clean out the data stored in the output bus holder, so please just skip this dummy read data and the target RAM data can be read out from the second read cycle.



Write Timing



Read Timing



Display RAM Address Mapping

The IST3932 embedded a one-on-one bit-pixel mapping display RAM to storage the display image data. The RAM size is 65(row) x 196(column) bits. Each pixel can be selected when the row and column addresses are specified. Data is read from or written to by 8-bit width through DB0 to DB7. The display data & LCD display mapping is illustrated as below.

The display RAM is designed with two ports, so when display is turned on, the internal LCD display operation and MPU display RAM access is independent and will not affect each other

ADC 0	AX					00H							01	1H				()2F							18ŀ	1							19	Н			
ADC=0	Data		D7	D6 D5	5 E	04 D3	3 [)2D	1 D0	D7	D6	D5	D4	D3[)2	D1 D	0 1	D7		D0		D7	D6	D	5 E)4 E)3)2E)1 D	0	D7 D	6	D5I	D 4	D3	D2	D1	D0
SHL=0	SHL=1	ΑY	seg1	seg2 seg3	,	seg4	0800	seg6	seg?/	sed9	seg10	seg11	seg12	seg13	seg14	seg15	20800	seg17	::	seg24		seg193	seg194	con105	60 600	seg196	×	××	< >	<	× ×	<	×	×	×	×	×	×
COM1	COM65	00H		Add	Ire	ess 0	00	00H			Α	dd	res	s 000)1I	Н		00	02	Н		A	*	ŧ	0	018	зН		4				(01	9H			
COM2	COM64	01H		Add	lre	ess 0	1(HOC			Α	dd	res	s 010)1I	Н		01	02	Н	4				0	118	зн						C)11	9Н			
СОМЗ	COM63	02H		Add	Ire	ess 0	20	00H		Address 0201H						02	202	H		-			0	218	ЗН				0219H									
COM4	COM62	03H		Add	Ire	ess 0	30	HOC		Address 0301H						Н		03	302	Н	Ħ.			4	0	318	ЗН				0319H							
COM5	COM61	04H		Add	Ire	ess 0	4(HOC			Α	dd	res	s 040)1I	Н	4	04	102	H		0418H				04191			9H									
COM6	COM60	05H		Add	Ire	ess 0	5(HOC			Α	dd	res	s 050)1ļ	H		0502H			4				0	518	ЗН			0519H								
COM7	COM59	06H		Add	Ire	ess 0	60	HOC			Α	Address 06			0601H			06	02	H					0	618	ЗН						C	61	9H			
COM8	COM58	07H		Add	Ire	ess 0	7(HOC			Addre			s 070)1I	H		07	702	Н					0	718	ЗН						C	71	9H			
												4		1																								
COM62	COM4	3DH		Add	re	ss 3	D	00H		4	A	ddı	ress	3D	01	H		30	002	H					3	D18	ЗН						3	D1	9H			
COM63	СОМЗ	3EH		Add	lre	ess 3	E	00H	- Alle	4	Α	ddı	ress	s 3E	01	Ĥ	4	3E	02	Н					3	E18	ЗН						3	E1	9H			
COM64	COM2	3FH		Add	lre	ess 3	F	00H	4		A	ddı	ress	s 3F	011	H		3F	02	Н					3	F18	ЗН						3	F1	9H			
COM65	COM1	40H		Add	Ire	ess 4	00	HOC		4	A	dd	res	s 400)1I	Н		40	02	Н						018								101	9H			
SHL=0	SHL=1	ΑY	×	××		××	***	××	×	×	×	×	×	seg1	seg2	seg3	655	Seg5	::	Seg12	:	Seg181	Seg182	Sec. 183	600	Seg184	Seg185	Seg186	Seg 187	ool fac	Seg189	061620	Seg191	Seg192	seg193	seg194	seg195	seg196
ADC=1	AX		A		-	19H	More							18H				17H				01H				0H												
ADC=1	Data		D0	D1 D2	2[03 D4	4 E	05 D	6 D7	7 D0	D1	D2	D3	D4[)5	D6D	7 I	D0		D7		DO	D1	D	20	3)4	D5 E)6D	7	D0 D	1	D2I)3	D4	D5	D6	D7

Reset Initialization

The IST3932 provides both hardware (H/W) reset and software (S/W) reset function. When the RESB is setting to "L", the H/W reset will be activated, or user can use S/W reset instruction to initialize the internal registers' configurations, but the H/W reset and S/W reset covered range is different, please check the table listed as below.

The default H/W reset initializing settings are listed as below:

No.	Register	Description
1.	DON=0	Display OFF
2.	REV=0	Reverse display OFF
3.	ADC=1	SEG output direction SEG196 → SEG1
4.	SHL=0	COM output direction COM1 → COM65
5.	(internal status)	Serial interface internal register data clear
6.	BS=0	LCD bias
7.	EON=0	Entire display OFF
8.	AY=0	Row address
9.	AX=0	Column address
10.	(internal status)	SEG/COM output GROUND level
11.	RMW=0	Read-Modify-Write OFF
12.	ST=0	Display start line address = 0
13.	CT=0000_0000	Electronic volume register

★ For S/W reset, only the 1 ~ 12 items above will be reinitialized.

When doing the H/W reset (RESB = "L"), the V0 will also discharge to GROUND level internally, so when using external LCD power sources, please input these power sources only when the H/W reset process has been finished (RESB is backing to "H").

Command Table

* : Don't care

MAY. 2013

NO.	INSTRUCTION	Α0	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Description
1	Set AY(2B)	0	0	0	0	0	0	AY3	AY2	AY1	AY0	Set column address LSB
		0	0	0	0	0	1	*	AY6	AY5	AY4	Set column address MSB
2	Power Control	0	0	0	0	1	0	1	1	VC	VF	Power control
3	Select LCD Bias	0	0	0	0	1	1	0	BS2	BS1	BS0	Set LCD bias
4	Sleep Mode	0	0	0	0	1	1	1	0	0	SLP	Power save mode 1:sleep
5	OSC Control	0	0	0	0	1	1	1	0	1	OSCO FF	0: OSC on; 1:OSC off
6	Display On/Off	0	0	0	0	1	1	1	1	0	DON	Turn on/off LCD 0:off;1:on
7	Set Starting	0	0	0	1	0	0	ST3	ST2	ST1	ST0	Set starting line -LSB
,	Line(2B)	0	0	0	1	0	1	*	ST6	ST5	ST4	Set starting line -MSB
8	Driver Display Control	0	0	0	1	1	0	SHL	ADC	EON	REV	Driver display control
9	S/W reset	0	0	0	1	1	1	0	1	1	0	Soft reset
10	Set Duty(2B)	0	0	1	0	0	_1	DUTY3	DUTY2	DUTY1	DUTY0	Set duty-LSB
10	Get Duty(2B)	0	0	1	0	1	0	*	DUTY6	DUTY5	DUTY4	Set duty-MSB
11	Set AX Address	0	0	1	1	0	AX4	AX3	AX2	AX1	AX0	Set AX address
12	Read Status	0	1	BUSY	ADC	DONB	RESB	0	0	0	0	Read the internal status
13	SPI3&SPI4 Read Status Command	0	0	0	1	1	1	1	0	0	0	SPI3&SPI4&IIC read status command
14	Write Display Data	1	0				Write	Data				Write data into display RAM
15	Read Display Data	1	1				Read	Data				Read data from display RAM
16	SPI3&SPI4 Read Ram Command	0	0	0	1	1	1	0	1	1	1	SPI3&SPI4 read ram data command
17	Reference Voltage	0	0	⁻ 1	0	1	1	0	0	0	1	Set reference voltage
17	Select(2B)	O	O	CT7	CT6	CT5	CT4	СТЗ	CT2	CT1	CT0	mode
				1	0	1	1	0	0	1	0	
18	Frame Control (3B)	0	0	LN7	LN6	LN5	LN4	LN3	LN2	LN1	LN0	Set frame control
				LN15	LN14	LN13	LN12	LN11	LN10	LN9	LN8	
19	NOP	0	0	1	1	1	0	0	0	1	1	No operation (dummy command)
20	MTP command entry	0	0	1	0	0	0	0	0	0	0	MTP command entry
21	MTP CT Offset enable select	0	0	0	0	0	1	1	0	CTOFT E	0	MTP CT offset enable select
22	MTP Program Enable	0	0	1	1	1	0	1	1	0	0	Programming enable
23	MTP Program Start	0	0	0	0	1	0	0	0	0	0	Programming start

Document No.:IST-RD-0125 Version: 003

24	MTP CT Offset	0	0	0	0	1	0	0	1	1	0	CT offset (2B)
24	(2B)			*	*	*	CTOFT 4	CTOFT 3	CTOFT 2	CTOFT 1	CTOFT 0	OT oliset (2D)
25	MTP Manually	0	0	1	0	1	0	0	0	1	0	MTP manually ADR
25	ADR			*	ADR[6]	ADR[5]	ADR[4]	ADR[3]	ADR[2]	ADR[1]	ADR[0]	,
26	Command Register Read Enable	0	0	1	0	0	0	1	1	0	0	Command register read enable
27	IST Command Entry	0	0	1	0	0	0	1	0	0	0	IST command entry, for some hardware operation configuration, it need repeat 4 times to enter
28	COM Mapping	0	0	0	1	1	0	0	0	0	MAP_ MODE	Set com pad map sequence
29	Exit Entry	0	0	1	1	1	0	0	0	1	1	Exit to normal command access

COMMAND DESCRIPTION

1. Set AY (ROW) Address

Set the AY address of display data RAM for MPU Write/Read access. After setting the AY (row) and/or AX (column) address, user can write/read the internal display RAM consecutively. When the AX (Column) address auto-incremented at the end, the AY address will auto-incremented by +1.

Α0	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	0	0	AY3	AY2	AY1	AY0
0	0	0	0	0	1	*	AY6	AY5	AY4

Note: Avoid setting AX before AY

2. Power Control

Internal Power supply circuits On/Off control. For details please refer to the "Power Supply Circuits" section.

A0	RW	DB7	DB6	DB5	DB4 DB3	DB2	DB1	DB0
0	0	0	0	1	0 1	1	VC	VF

3. Select LCD Bias

Selects LCD bias ratio of the voltage required for driving the LCD.

Α0	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	1	1	0	BS2	BS1	BS0

4. Sleep Mode

Sleep mode only happen at SLP=1, It'll stop all the operations in this chip, as long as there are no accesses from the MPU, the power consumption is close to the static leakage current.

set SLP=0 to exit sleep mode

The internal status during sleep mode is as below:

- a) The oscillator circuit and the LCD power supply circuit are turned off.
- All liquid crystal drive circuits are stop, all the LCD driving outputs (SEGx/COMx) output GROUND level.

Α0	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	1	1	1	0	0	SLP

5. OSC Control

Α0	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	1	1	1	0	1	OSCOFF

Document No.:IST-RD-0125 Version: 003 MAY. 2013

The oscillator circuit will be turned off when OSCOFF set "H"

6. Display ON / OFF

LCD display ON / OFF select

Α0	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	1	1	1	1	0	DON

DON = 1 Display ON

DON = 0 Display OFF

7. Set Starting Line

Set the starting line address for the first common output.

Α0	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	1	0	0	ST3	ST2	ST1	ST0
0	0	0	1	0	1	*	ST6	ST5	ST4

ST6	ST5	ST4	ST3	ST2	ST1	ST0	Line address
0	0	0	0	0	0	0	0
0	0	0	0	0	0	1	1
1	0	0	0	0	0	0	64

8. Driver display control

-	10	RW	DB7 DB6	DB5	DB4	DB3	DB2	DB1	DB0
()	0	0 1	1	0	SHL	ADC	EON	REV

SHL: Select (Common Output Mode Select)

SHL = 0: COM1 \rightarrow COM_N SHL = 1: COM_N \rightarrow COM1

N define as duty setting, reference as "SET DUTY".

ADC:

Defines the relationship between RAM column address and segment driver. The detailed mapping please referred to the "Display RAM Address Mapping" chapter.

ADC = 0: SEG1 → SEG196 ADC = 1: SEG196 → SEG1

EON:

Forces the whole LCD points to be turned on regardless of the contents of the display data RAM. This instruction will not change the original display RAM data and has higher priority than the reverse display ON / OFF instruction.

EON = 0: Normal display EON = 1: Entire display ON

REV:

Reverse the lit and unlit display relation between RAM bit data and LCD cell. This setting will not change the original display RAM data.

REV	RAM bit data = "1"	RAM bit data = "0"
0	LCD pixel will accumulated ON voltage	LCD pixel will accumulated OFF voltage
1	LCD pixel will accumulated OFF voltage	LCD pixel will accumulated ON voltage

9. S/W Reset

This instruction will activate the internal S/W reset operation. The covered ranged is different with H/W reset, for details please refer to the "Reset Initialization" section.

Α0	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	1	1	1	0	1	1	0

10. Set Duty

This instruction will activate the internal S/W reset operation. The covered ranged is different with H/W reset, for details please refer to the "Reset Initialization" section.

Α0	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	1	0	0	1	DUTY3	DUTY2	DUTY1	DUTY0
0	0	1	0	1	0	*	DUTY6	DUTY5	DUTY4

DUTY6	DUTY5	DUTY4	DUTY3	DUTY2	DUTY1	DUTY0	Duty Ratio
0	0	0	0	0	0	0	reserve
0	0	0	0	0	0	1	1/1
1	0	0	0	0	0	0	1/64
1	0	0	0	0	0	1	1/65

After setting DUTY, Com1~COM_N is select, N=DUTY[6:0].

11. Set AX Address

Sets the Column Address of display data RAM for MPU Write/Read access. After setting the row and/or Column address, user can write/read the internal display RAM consecutively. The Column address will auto-incremented by +1 .

Α0	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	1	1	0	AX4	AX3	AX2	AX1	AX0

12. Read Status

Α0	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	1	BUSY	ADC	ON/OFF	RESB	0	0	0	0

Flag	Description
BUSY	BUSY = 1 : The chip is still under processing, including reset initialization BUSY = 0 : The chip is free to accept MPU commands
V176.	ADC = 1 : SEG direction is SEG196 → SEG1 ADC = 0 : SEG direction is SEG1 → SEG196
	ON/OFF = 1 : Display is turned off ON/OFF = 0 : Display is turned on * The polarity is reversed with DON command!
RESET	RESET = 0 : The chip is doing the H/W or S/W reset RESET = 1 : The chip is not doing the reset operation

13. SPI3 & SPI4 read status command

Indicate the internal status. When use SPI3, SPI4 or IIC interface, it must send the command 78H before read operation.

Α0	RW	DB7 DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	1	0 1	1	1	1	0	0	0

Only use in SPI3, SPI4 or IIC interface

14. Write Display Data

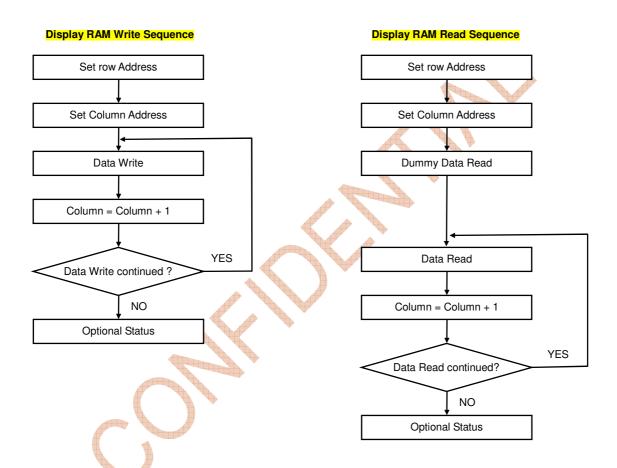
8-bit display data can be written to the display RAM location specified by the column address and row address by this instruction. The column address is increased by 1 automatically so that the microprocessor can continuously write data to the addressed rows.

Α	.0	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
-	1	0				Write	data			

15. Data Read Display Data

8-bit display data RAM specified by the column address and row address can be read by this instruction. As the column address is increased by 1 automatically after each this instruction, the microprocessor can continuously can continuously read data from the addressed row. A dummy read is required after specified the target column and/or row address.

A0	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
1	1				Read	data			



16. SPI3 & SPI4 read ram command

When use SPI3, SPI4 or IIC interface, it must send the command 77H before read operation.

Δ	۷0	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
	0	0	0	1	1	1	0	1	1	1

Only use in SPI3, SPI4 or IIC interface

17. Reference Voltage Select (double byte command)

The Reference voltage select instruction consists of 2-byte command. The 1st instruction sets reference voltage mode and the 2nd one is the contents of reference voltage register. These two instructions must be executed adjacently or the following commands sequence will be misinterpreted and lead to unexpected results.

The 1st instruction: Set Reference Voltage Select Mode

Α0	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	1	0	1	1	0	0	0	1

The 2nd instruction: Set Reference Voltage Register

Α0	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	CT7	CT6	CT5	CT4	СТЗ	CT2	CT1	CT0

СТ7	СТ6	CT5	СТ4	СТЗ	CT2	CT1	СТ0	Reference voltage Parameter (α)	V0	Contrast
0	0	0	0	0	0	0	0	0 (default)	Minimum	Low
0	0	0	0	0	0	0	1	4		
:					:	:			:	:
1	0	0	0	0	0	0	0	128	:	:
:	:	:	:	:	:		A. A.		:	:
1	1	1	1	1	1	1	0	254		
1	1	1	1	1 (1	1	1	255	Maximum	High

V0 calculation: V0= [0.7+CT*0.005]/Bias at 24° C, if the MTP is Pre-programmed

or V0= [0.7+ (CT+CTOFT)*0.005]/Bias (if using the MTP Programmed)

<Example> CT =3CH, Bias=1/9, then V0=(0.7+60*0.005)/(1/9)=9.0V

18. Frame Control (Three bytes command)

The **Frame Control** instruction consists by three commands. The 1^{st} instruction sets **Frame Control** mode, the 2^{nd} and 3^{rd} command set the Frame frequency DIV number

The 1st instruction: sets Frame Control mode

A0	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	1	0	1	1	0	0	1	0

The 2nd and 3rd instruction:

A0	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	LN7	LN6	LN5	LN4	LN3	LN2	LN1	LN0
0	0	LN15	LN14	LN13	LN12	LN11	LN10	LN9	LN8

LN15~0: DIV number by inside oscillator (3MHZ)

Row frequency = 3×10^6 / (LN15~0+1) Frame frequency = Row frequency / DUTY6~0 (at 25 °C)

19. NOP

No-Operation command (dummy command).

A0	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	1	1	1	0	0	0	1	1

MTP Command Table

INSTRUCTION	Α0	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
MTP CT Offset enable select	0	0	0	0	0	1	1	0	CTOFTE	0
Programming Start	0	0	0	0	1	0	0	0	0	0
CT offset (2B)	0	0	0	0	1	0	0	1	1	0
CI OIISEC (ZB)	U		*	*	*	CTOFT4	CTOFT3	CTOFT2	CTOFT1	CTOFT0
MTP Manually ADR	0	0	1	0	1	0	0	0	1	0
MIP Manually ADR	U	0	*	ADR[6]	ADR[5]	ADR[4]	ADR[3]	ADR[2]	ADR[1]	ADR[0]
Command register read enable	0	0	1	0	0	0	1	1	0	0
Programming Enable	0	0	1	1	1	0	1	1	0	0

CTOFT[4:0]	STEP
0x00	0
0x01	+1
0x0F	+15
0X10	-16
0X11	-15
0X1F	-1

20. MTP Command Entry (80h, repeat 4 times)

Α0	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	1	0	0	0	0	0	0	0

IST3932 embedded MTP (Multi-Time-Programming) memories for users to store individual settings by modules to keep a consistent display quality. User can use 80h command to enter the MTP command mode and then the following commands will be interpreted as MTP commands (listed as above). After the MTP commands' setting have been finished, use NOP (E3h) command can leave the MTP command section and then back to the normal command section.

After entered the MTP command section, user can first use the provided MTP adjustable parameters to preview the adjusted display results, after the display quality has been satisfied, then set the enable select bit and use MTP Program Enable (ECH) and MTP Program Start (20H) command to start programming all the ready registered settings into MTP memory cells at the same time. After the MTP programming has been be finished, the programmed MTP values will be automatically reloaded.

21. MTP CT Offset enable select

A 0	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	0	T	1	0	CTOFTE	0

CTOFTE=0, disable; CTOFTE=1, enable.

22. MTP Program Enable

A0	RW	DB7 DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	1	1	0	1	1	0	0

23. MTP Program Start

Α0	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	1	0	0	0	0	0

Once execute MTP Program Enable (ECH) command and MTP Program Start (20H) the MTP programming section is enabled and waiting for the MTP Program Start command to automatically starts the whole MTP programming section.

24. MTP CT Offset

A0	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	1	0	0	1	1	0
		*	*	*	CTOFT4	CTOFT3	CTOFT2	CTOFT1	CTOFT0

25. MTP Manually ADR

A0	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	1	0	1	0	0	0	1	0
		*	ADR[6]	ADR [5]	ADR[4]	ADR[3]	ADR[2]	ADR[1]	ADR[0]

When ADR[6:0] = 0X1E, the read out data is CTOFT.

26. Command Register Read Enable

Α0	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	1	0	0	0	1	1	0	0

MTP Write Flow

The suggested MTP write flow is listed as below: (Where the VPP Pin supplied 7.0v.)

MTP Write Flow

				— — — — — — — — — — — — — — — — — — —
Step	Α0	RW	Command	Description
0			(Initial)	Set Display ON, Power Configuration, Contrast (SV), etc.
1 step1	0	0	80h	■ Enter MTP command mode
1 ^{step2}	0	0	80h	Enter MTP command mode
1 ^{step3}	0	0	80h	■ Enter MTP command mode
1 ^{step4}	0	0	80h	■ Enter MTP command mode
2 ^{A1}	0	0	CTOFT	■ MTP CTOFT adjust (1Fh~00h) if doing the SV offset adjust
3	0	0	MTP Enable Select	■ Set Enable bit for CTOFTEand so on
4	0	0	ECh	■ MTP Program enable
5	0	0	20h	■ MTP Program Start
6	0	0	(Waiting)	MTP programming section, idle about 10ms to wait the MTP programming section finished
7	0	0	E3h	■ Use NOP command to release MTP command mode
8			(Initial)	■ Set Display ON, Power Configuration, Contrast (SV), etc.

Annotation -

A1: maybe need some iteration to get the best display result.

MTP Read Flow

The MTP memory cells data can be read back through parallel interfaces. The suggested MTP read flow is listed as below: (Where the VPP Pin keeps Floating.)

MTP Read Flow

Step	A 0	RW	Command	Description
1 step1	0	0	80h	■ Enter MTP command mode
1 ^{step2}	0	0	80h	■ Enter MTP command mode
1 ^{step3}	0	0	80h	■ Enter MTP command mode
1 ^{step4}	0	0	80h	■ Enter MTP command mode
2	0	0	Set MTP Address	■ Set MTP read address (MTPRA=1EH)*
3	0	0	8ch	■ Enter Read mode
4	0	1	Read operation	■ Read data from MTP
5	0	0	E3h	■ Use NOP command to release MTP command mode

^{*}Note: 1EH store the value of CTOFT.

27. IST Command Entry

Α0	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	1	0	0	0	1	0	0	0

IST command entry, for some hardware operation configuration, it need repeat 4 times to enter

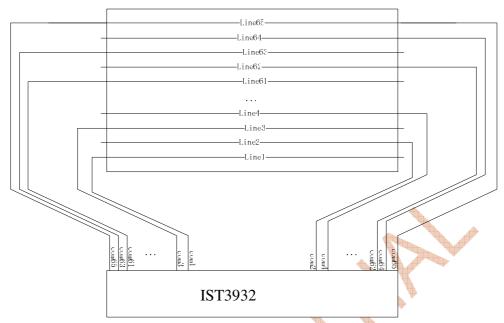
28. COM Mapping

Α0	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	1	1	0	0	0	0	MAP_MODE

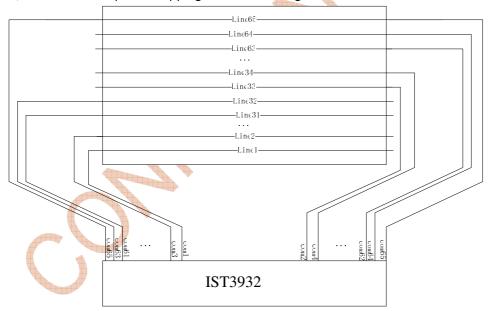
Set com pad map sequence

MAP_MODE=0, COM65~1 and panel mapping show as next figure:

^{*}MAP_MODE default is 1.



MAP_MODE=1, COM65~1 and panel mapping show as next figure:



29. Exit Entry

A0	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	1	1	1	0	0	0	1	1

Exit to normal command access

IST command write Flow

Step	Α0	RW	Command	Description
1 ^{step1}	0	0	88h	■ Enter IST command mode
1 ^{step2}	0	0	88h	■ Enter IST command mode
1 step3	0	0	88h	■ Enter IST command mode
1 ^{step4}	0	0	88h	■ Enter IST command mode
2	0	0	Set set MAP_MODE	■ Set set MAP_MODE
3	0	0	E3h	■ Use NOP command to release IST command mode



Power Supply Circuits

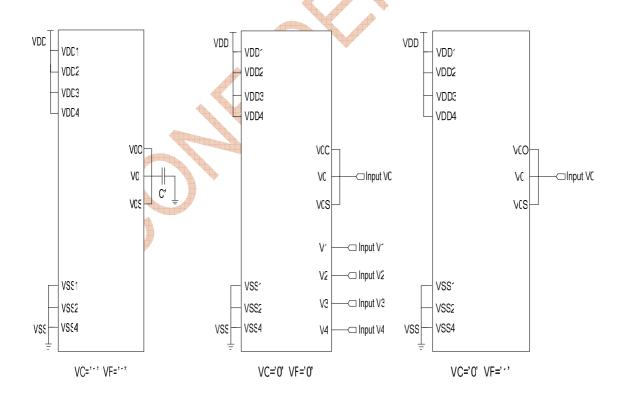
The Power Supply circuits generate the voltage levels necessary to drive liquid crystal driver circuits with low power consumption and the fewest components. There are two modules, voltage converter circuits (VC) and voltage follower circuits (VF). They are valid only in master operation and controlled by power control instruction. The possible LCD power supply configurations are listed as below.

Power Supply Configurations

Power Configuration	Instruction (VC VF)	VC circuits	VF circuits	V0O V0I V0S* ¹	V1 to V4
Internal power supply circuits are used	(11)	ON	ON	Open*1	Open*2
Only the voltage follower circuits are used	(01)	OFF	ON	External input	Open*2
Only the external power supply circuits are used	(00)	OFF	OFF	External input	External input

<Note>

* 1 V0O, V0I and V0S are short together by ITO. When VC="1", connect external stabilizing capacitors to GROUND.



C*=0.01~4.7uF

Voltage Follower Circuits

The Voltage Follower circuits resistively divide the liquid crystal operating voltage (V0) into four voltage levels (V1, V2, V3 and V4) and these voltage levels will be buffered output to serve as the LCD driving power sources.

BS<2>	BS<1>	BS<0>	Bias	V1	V2	V3	V4
1	0	1	1/11	10/11 x V0	9/11 x V0	2/11 x V0	1/11 x V0
0	0	1	1/10	9/10 x V0	8/10 x V0	2/10 x V0	1/10 x V0
0	0	0	1/9*	8/9 x V0*	7/9 x V0*	2/9 x V0*	1/9 x V0*
0	1	0	1/8	7/8 x V0	6/8 x V0	2/8 x V0	1/8 x V0
0	1	1	1/7	6/7 x V0	5/7 x V0	2/7 x V0	1/7 x V0
1	0	0	1/6	5/6 x V0	4/6 x V0	2/6 x V0	1/6 x V0

* Default Value

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Rating	Unit
Supply voltage range	VDD1/VDD2/ VDD3	-0.3 ~ 7	V
	V0	-0.3 ~ 13.5	V
Supply voltage range	V1/V2/V3/V4	-0.3 ~ V0	V
Input voltage range	VIN	-0.3 to VDD1 + 0.3	V
Operating temperature range	Topr	-30 to +80	°C
Storage temperature range (Bare chip)	Tstr	-55 to +125	°C

NOTES:

- 1. VDD1/VDD2/VDD3 and V0 are based on VSS1/VSS2/VSS4 = 0V
- 2. The Voltage levels relation $V0 \ge V1 \ge V2 \ge V3 \ge V4 \ge VSS1/VSS2/VSS4 = 0V$ must always be satisfied.
- 3. If supply voltage exceeds the absolute maximum range, this LSI may be damaged permanently.

DC CHARACTERISTICS

(Ta = -30 to 80°C)

Item		Symbol	Condition	Min.	Тур.	Max.	Unit	Pin used
Operating Volta	age(1)	VDD1		2.4	-	3.6	٧	VDD1 *1
Operating Voltage(2)		VDD2~4		2.4	-	3.6	٧	VDD2~4 *9
Operating Volta	age(3)	V0O/V0I/ V0S		4.0	-	13.5	٧	V0O/V0I/ V0S *2
Input voltage	High	VIH		0.8*VDD1	-	VDD1	V	*3
input voitage	Low	VIL		Vss1	-	0.2*VDD1	V	
Output voltage	High	Vон	IOH = -0.5mA	0.8*VDD1		VDD1	٧	*4
Output voltage	Low	Vol	IOL = 0.5mA	Vss1	-	0.2*VDD1	V	4
Input leakage current		lıL	VIN = VDD1 or VSS1	-1.0	-	+1.0	μΑ	*5
Output leakage	current	I _{OL}	VIN = VDD1 or VSS1	-3.0	-	+3.0	μΑ	*6
LCD driver (Resistanc		R _{ON}	$Ta = 25^{\circ}C, V0 = 13V$	-	2.0	3.0	kΩ	SEGn COMn *7
Oscillator frequence (internal)		F _{osc}	Ta ≥ 25°C	2.8	3.0	3.2	MHz	
Oscillator freq (External		F _{CL}	Ta = 25°C	2.8	3.0	3.2	MHz	CL
MTP program	ming	VPP	No loading	6.8	7.0	7.2	>	VPP
voltage		IPP	·			3	mA	VI-E
LCD operation '	Voltage	VO	Ta = 25°C, CT=3C, bias=1/9 Booster X5 VDD1=VDD2=VDD4=3.3V	8.9	9	9.1	٧	V0

Dynamic Current Consumption

 $(Ta = 25^{\circ}C)$

Item	Symbol	ymbol Condition		Тур.	Max.	Unit	Pin used
Dynamic current consumption	I _{DYN}	VDD2=VDD1= 3.3V X5 Boost V0 – GROUND = 9.0V Display ON (HPMB=1, Checker pattern)	-	300	400	μΑ	*8 I _{VDD1+VDD2+} VDD3

Static Current Consumption

(Ta =25°C)

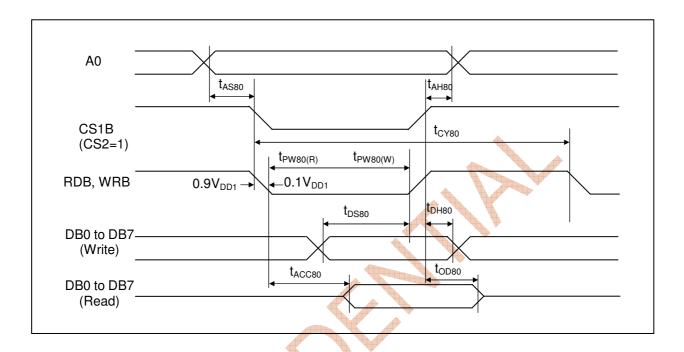
Item	Symbol	Condition	Min.	Тур.	Max.	Unit	Pin used
Sleep mode current	I _{SLP}	Sleep mode, VDD1=VDD2~VDD3=3.3V	_	1	5	μΑ	I _{VDD1+VDD2+} VDD3

NOTE

- *1. Although the wide range of DC operating voltages is guaranteed, but if the voltage fluctuation is too large during MPU accessing, the performance can't be guaranteed.
- *2. In case of external power supply is applied.
- *3. CS1B, CS2, A0, DB0~ DB7, E_RDB, RW_WRB, RESB, C68, PS, CLS, CL, pins.
- *4. DB0 ~ DB7
- *5. CS1B, CS2, A0, DB [7:0], E_RDB, RW_WRB, RESB, C68, PS, CLS, CL pins.
- *6. Applies when the DB0 ~ DB7pins are in high impedance.
- *7. Resistance value when 0.1 mA is applied during the ON status of the output pin SEGn or COMn. RON= $\Delta V / 0.1$ [K Ω] (ΔV : voltage change when 0.1 mA is applied in the ON status.)
- *8. Applies to the case where the on-chip oscillation circuit is used and no access is made from the MPU & the LCD outputs (COMx, SEGx) are just floating, without any loading

AC CHARACTERISTICS

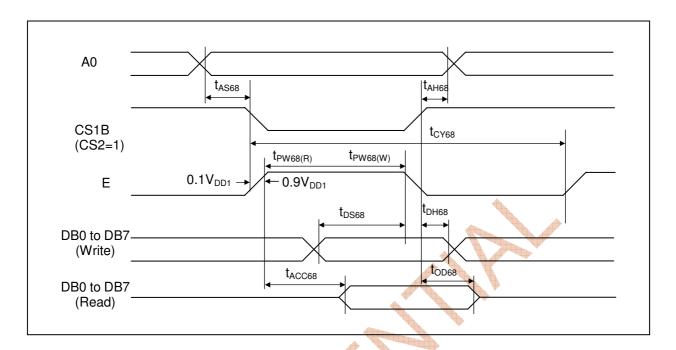
Read / Write Characteristics (8080-series MPU)



 $(VDD1 = 2.4 \sim 3.6V, Ta = -30 \sim 80 °C)$

Item	Signal	Symbol	Min.	Тур.	Max.	Unit	Remark
Address setup time Address hold time	A0	tAS80 tAH80	0 0	-	-	ns	
System cycle time		tCY80 (W)	300	-	-	ns	
		tCY80(R)	500	-	1	ns	
Pulse width (WRB)	RW_WRB	tPW80(W)	150	-	ı	ns	
Pulse width (RDB)	E_RDB	tPW80(R)	250	-	ı	ns	
Data setup time Data hold time	DB7 to	tDS80 tDH80	60 0	-	-	ns	
Read access time Output disable time	DB0	tACC80 tOD80	140 -	-	- 10	ns	(No load)

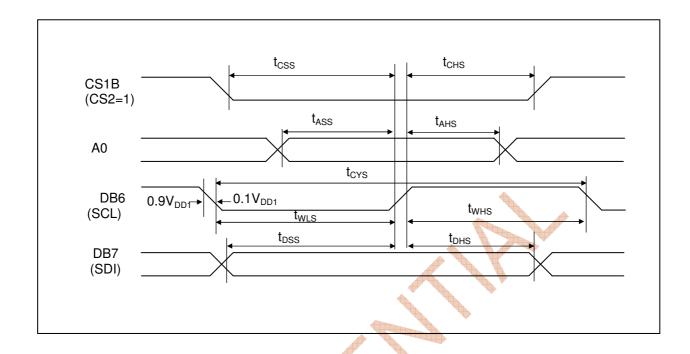
Read / Write Characteristics (6800-series Microprocessor)



 $(VDD1 = 2.4 \sim 3.6V, Ta = -30 \sim 80 \circ C)$

Item	Signal	Symbol	Min.	Тур.	Max.	Unit	Remark
Address setup time Address hold time	A0	tAS68	0 0	-	-	ns	
Systom systo timo		tCY68(W)	300	-	1	ns	
System cycle time		tCY68(R)	500	ı	ı	ns	
Pulse width (E)	RW_WRB	tPW68(W)	150	ı	ı	ns	
Pulse width (E)	E_RDB	tPW68(R)	250	-	-	ns	
Data setup t <mark>i</mark> me Data hold time	DB7 to	tDS68 tDH68	60 0	-	-	ns	
Read access time Output disable time	DB0	tACC68 tOD68	140 -	-	- 10	ns	(No load)

Serial Interface Characteristics

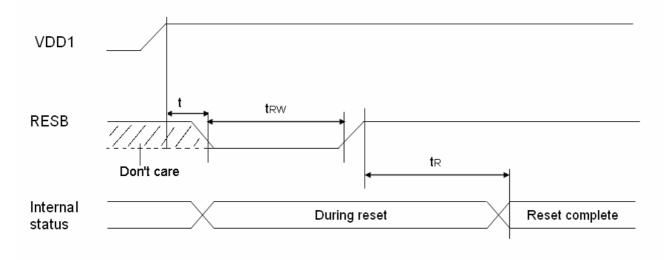


 $(VDD1 = 2.4 \sim 3.6V, Ta = -30 \sim 80 ^{\circ}C ^{\circ}C)$

Item	Signal	Symbol	Min.	Тур.	Max.	Unit	Remark
Serial clock cycle SCL high pulse width SCL low pulse width	DB6 (SCL)	tCYS tWHS tWLS	200 90 90	- - -	- - -	ns	
Address setup time Address hold time	A0	tass tahs	45 45	-	-	ns	
Data setup time Data hold time	DB7 (SDI)	tdss tdhs	45 45	-	-	ns	
CS1B setup time CS1B hold time	CS1B	tcss tchs	90 90	-	-	ns	

Note: All signal Rising time and falling Time <15ns

Reset Input Timing



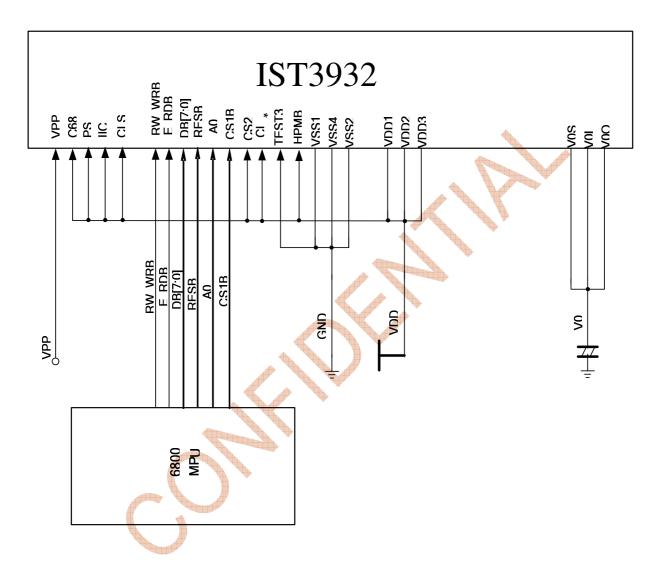
 $(VDD1 = 2.4V \sim 3.6V, Ta = -30 \sim 80^{\circ}C)$

			The state of the s	1		
Item	Signal	Symbol	Min. Ty	o. Max.	Unit	Remark
Reset low pulse width	RESB	tRW	2 -	-	us	
Reset time	-	tR	-	2	us	
Reset time	RESB		0 -	-	us	

REFERENCE APPLICATIONS

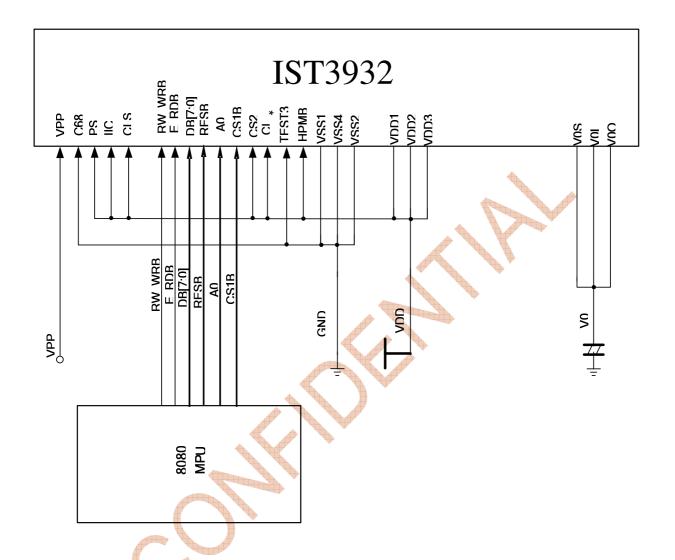
MPU Interface

In Case of Interfacing with 6800-series (PS = "H", C68 = "H", IIC=H)



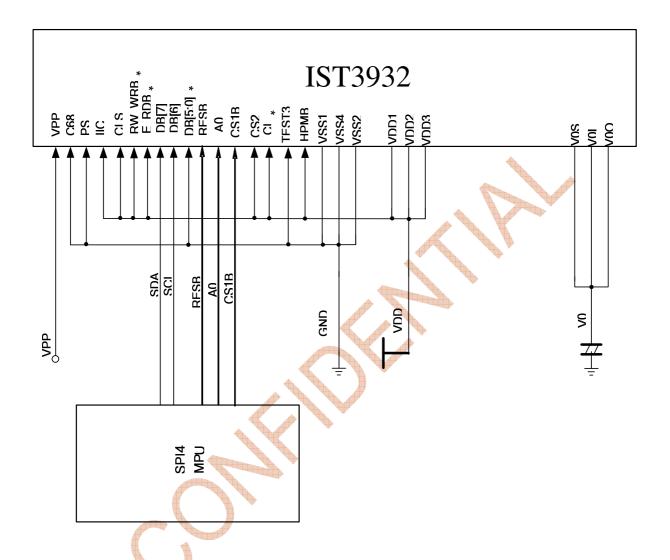
*: No use pin must fixed to VSS1 or VDD1

In Case of Interfacing with 8080-series (PS = "H", C68 = "L", IIC=H)



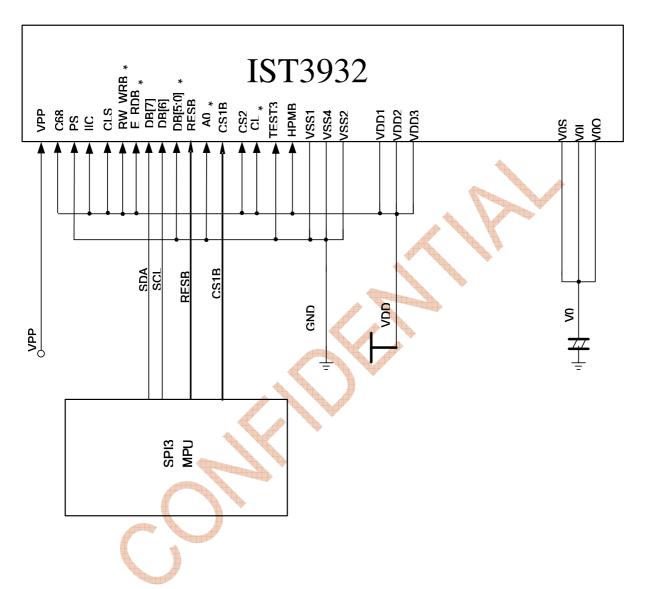
^{*:} No use pin must fixed to VSS1 or VDD1

In Case of Serial Interface 4 (PS = "L", C68 = "L", IIC=H)



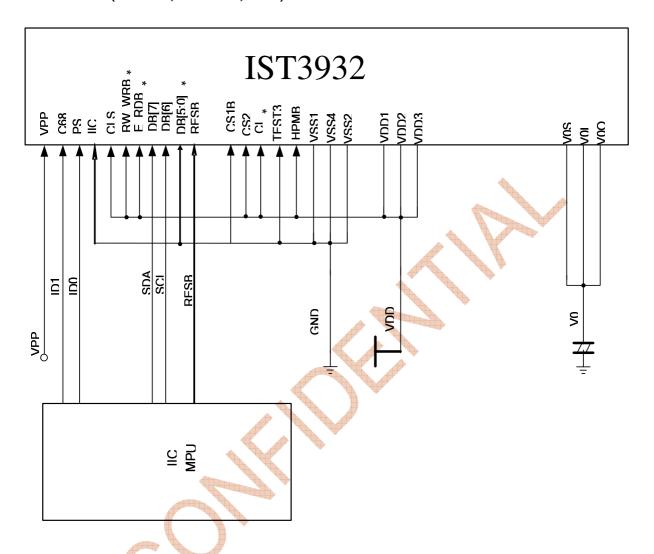
*: No use pin must fixed to VSS1 or VDD1

In Case of Serial Interface 3 (PS = "L", C68 = "H", IIC=H)



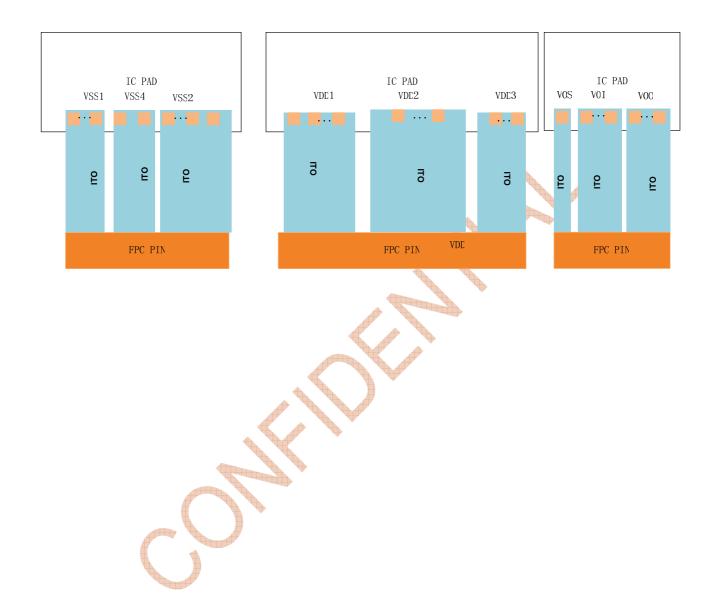
*: No use pin must be fixed to VSS1 or VDD1

In Case of IIC (PS = "X", C68 = "X", IIC=L)



*: No use pin must be fixed to VSS1 or VDD1

ITO CONNECTION



CAUTIONS:

- 1. This Specification will be subjected to modify without notice.
- 2.Precutions on Light:

Characteristics of semiconductor devices can be changed when exposed to light as described in the operational principles of solar batteries. Exposing this IC to light ,therefore ,can potentially lead to its malfunctioning.

- 2.1Care must be exercised in designing the operation system and mounting the IC so that it may not be exposed light during operation.
- 2.2Care must be exercised in designing the inspection process and handling the IC so that it may not be exposed to light during the process.
- 2.3The IC must be shielded from light in the front, back and side faces.

3.ESD control and prevention:

- 3.1Humidity Control:30~70% relative humidity is recommended.
- 3.2To reduce the risk of ESD, all equipment at the wok surface should be properly grounded and all sources of static fields removed.(Example: Station ionizers).
 - 3.3Grounding all personnel who come in contact with parts will eliminate a possible source of ESD.

(Example: Wrist straps remove charge from the body and constitute a central part of ESD control).

4. Storage Conditions:

Before open package	After open package
Temp.=25±5°C Humidity:50~70% Less than 1 Years	Temp.=25±5°C Humidity:50~70% Less than 3 Months